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Date: December 17, 2002

Sonia V. McVean
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1.3.02

PATENT
36856.366

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

<p>Applicant: Takao MUKAI et al.</p> <p>Serial No.: 09/692,668</p> <p>Filed: October 20, 2000</p> <p>Title: SURFACE ACOUSTIC WAVE DEVICE HAVING AN INTERDIGITAL TRANSDUCER PROVIDED ON A MAIN REGION OF A PIEZOELECTRIC SUBSTRATE</p>	<p>Art Unit: 2834</p> <p>Examiner: J. Gonzalez</p>
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INFORMATION DISCLOSURE STATEMENT

ASSISTANT COMMISSIONER FOR PATENTS
Washington, D.C. 20231

Dear Sir:

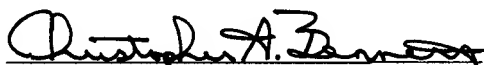
Pursuant to 37 C.F.R. § 1.56, submitted herewith are copies of seven (7) references cited in the enclosed opposition filed in a corresponding Japanese patent application. For the Examiner's convenience, we have enclosed an English translation of the Japanese opposition papers from the corresponding Japanese Patent Application and a completed Form PTO-1449. The statement is not a representation that all of the information cited is necessarily effective as prior art against the application.

I hereby state that each item of information contained in this Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application not more than 3 months prior to the filing of this statement, and that this is the first citation of these prior art references by a foreign patent office in a counterpart foreign patent application. Accordingly, no fee is necessary for the filing of this statement. Should the Commissioner determine otherwise, the Commissioner is authorized to charge Deposit Account No. 50-1353 for any fee shortages, including the petition fee under 37 C.F.R. § 1.17(p).

Applicant(s) respectfully request(s) that the disclosed reference(s) be made of record in the subject application.

Respectfully submitted,

Date: December 17, 2002

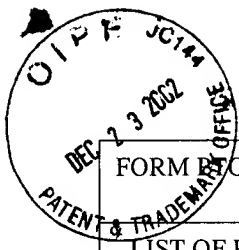


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FORM PTO-1449 (MODIFIED)	ATTY. DOCKET NO. 36856.366	SERIAL NO. : 09/692,668
LIST OF PATENTS AND PUBLICATIONS FOR APPLICANTS INFORMATION DISCLOSURE STATEMENT (USE SEVERAL SHEETS IF NECESSARY)	APPLICANT(S): Takao MUKAI et al.	
	FILING DATE: October 20, 2000	GROUP: 2834

Reference Designation

U.S. Patents

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Examiner Initial	Document Number	Date	Name	Class	Filing Date Subclass if appropriate
	AA				
	AB				
	AC				
	AD				
	AE				
	AF				
FOREIGN PATENT DOCUMENTS					
	Document Number	Date	Country	Class	Filing Date Subclass if appropriate
	AG 7-297074 (with English Abstract)	11/1995	Japan		
	AH 7-142904 (with English Abstract)	06/1995	Japan		
	AI 9-190947 (with English Abstract)	07/1997	Japan		
	AJ				
	AK				
	AL				
	AM				
	AN				
	A0				
OTHER ART (INCLUDING AUTHOR, TITLE, DATE, PERTINENT PAGES, ETC.)					
	AP M. O'NEILL; "A Low Temperature Co-Fire Ceramic Materials System for High Performance Commercial Applications"; ISPS '97 Proceedings, December 2-5, 1997; pp.135-140.				
	AR C. MAKIHARA et al.; "Multifunctional Ceramic Substrates and Packages for Telecommunication Applications"; ISHM '94 Proceedings Nov. 15-17, 1994; pp. 243-247.				
	AS M. KATO et al.; "Application of Low Temperature Fired Multilayered Substrates to High Frequency"; ISHM '92 Proceedings; Oct. 19-21, 1992; pp.263-268.				
	AT P.C. DONOHUE et al.; "High Reliability Copper MCM Systems"; ISHM '92 Proceedings, Oct. 19-21, 1992; pp. 607-612.				
EXAMINER	DATE CONSIDERED				
EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.					